



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Part Number: AAA3528LSEKJ3ZGKBKS

Hyper Red
Green
Blue

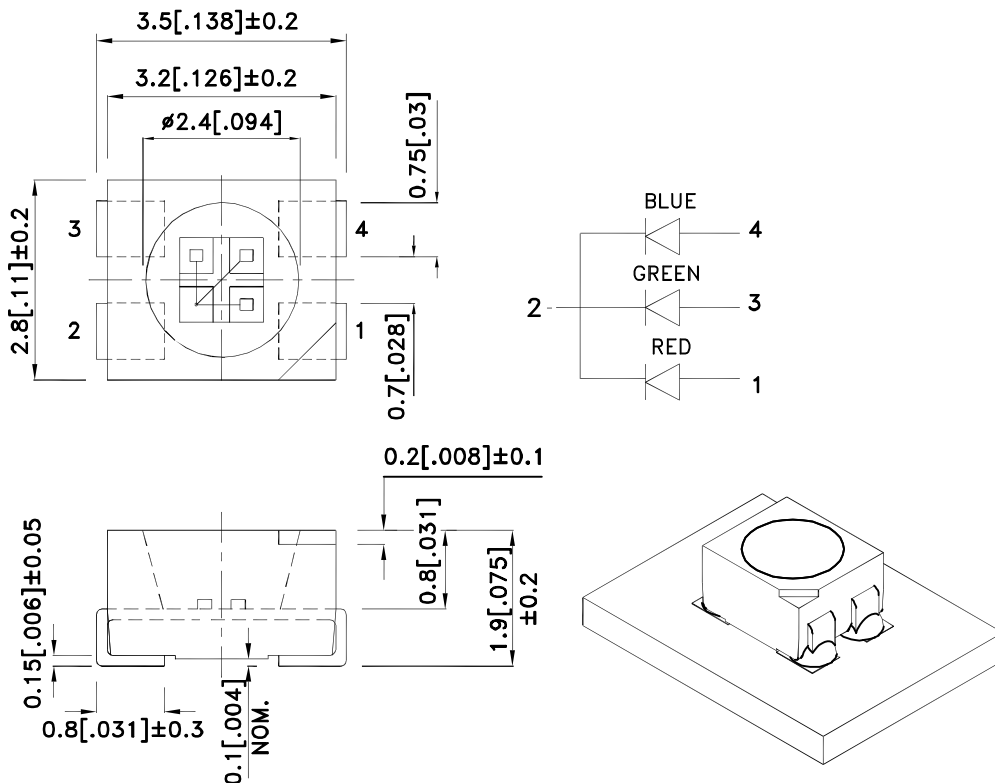
Features

- Suitable for all SMD assembly and solder process.
- Available on tape and reel.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- Low current IF=2mA operating.
- RoHS compliant.

Descriptions

- The Hyper Red device is based on light emitting diode chip made from AlGaInP.
- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode.
- The Blue source color devices are made with InGaN on Sapphire Light Emitting Diode.
- Electrostatic discharge and power surge could damage the LEDs.
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.
- All devices, equipments and machineries must be electrically grounded.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

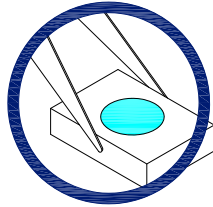


Handling Precautions

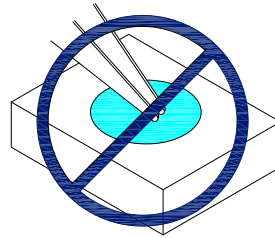
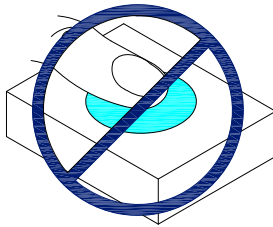
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly Orangeuces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

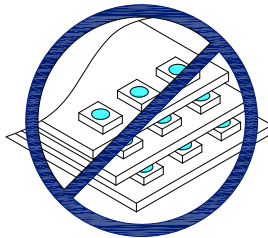
1. Handle the component along the side surfaces by using forceps or appropriate tools.



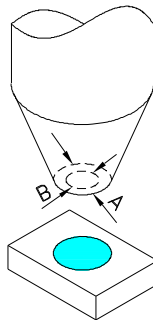
2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

Selection Guide

Part No.	Emitting Color (Material)	Lens Type	Iv (mcd) [2] @ 2mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
AAA3528LSEKJ3ZGKQBKS	Hyper Red (AlGaInP)	Water Clear	30	60	120°
	Green (InGaN)		80	180	
	Blue (InGaN)		12	30	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity / luminous Flux: +/-15%.
3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red Green Blue	640 515 460		nm	If=2mA
λD [1]	Dominant Wavelength	Hyper Red Green Blue	625 525 465		nm	If=2mA
Δλ1/2	Spectral Line Half-width	Hyper Red Green Blue	20 35 25		nm	If=2mA
C	Capacitance	Hyper Red Green Blue	27 45 100		pF	Vf=0V;f=1MHz
Vf [2]	Forward Voltage	Hyper Red Green Blue	1.8 2.65 2.65	2.1 3.1 3.1	V	If=2mA
Ir	Reverse Current	Hyper Red Green Blue		10 50 50	uA	VR=5V

Notes:

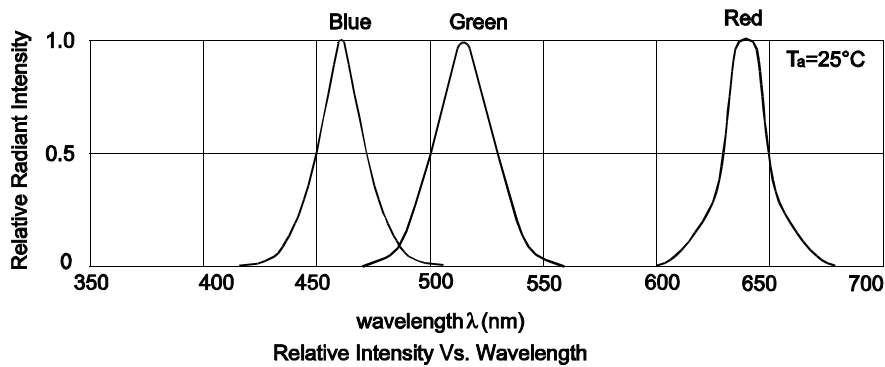
- 1.Wavelength: +/-1nm.
- 2.Forward Voltage: +/-0.1V.
- 3.Wavelength value is traceable to the CIE127-2007 compliant national standards.
- 4.Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Absolute Maximum Ratings at TA=25°C

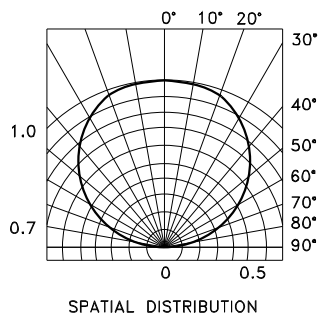
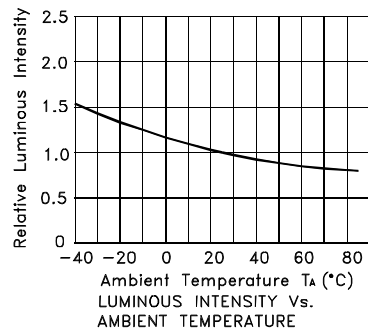
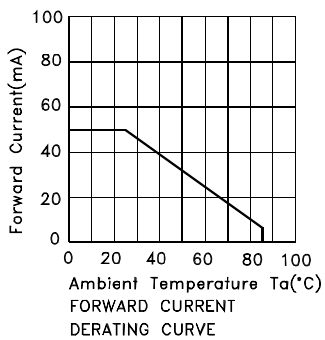
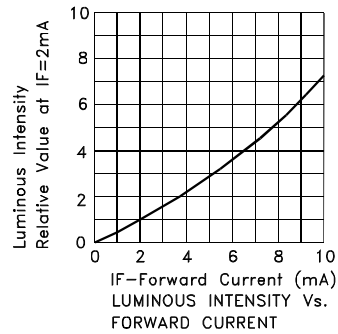
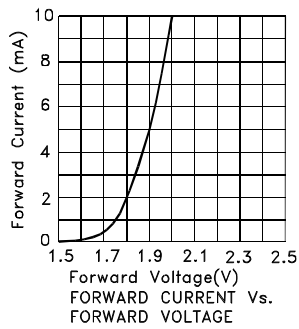
Parameter	Hyper Red	Green	Blue	Units
Power dissipation	105	93	93	mW
DC Forward Current	50	30	30	mA
Peak Forward Current [1]	150	150	150	mA
Electrostatic Discharge Threshold (HBM)	3000	450	250	V
Reverse Voltage	5			V
Operating Temperature	-40°C To +85°C			
Storage Temperature	-40°C To +85°C			

Notes:

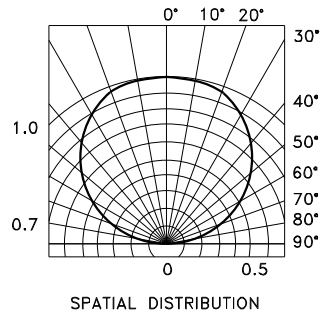
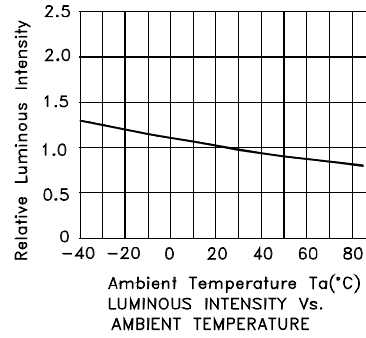
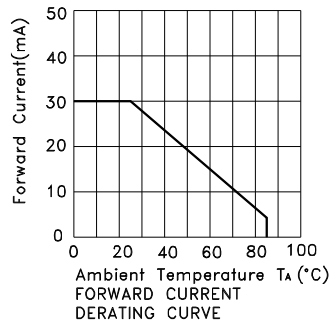
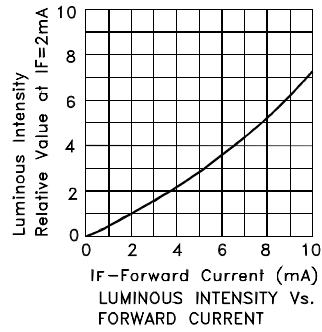
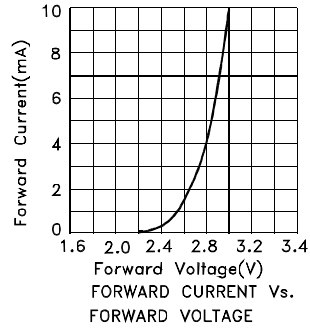
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



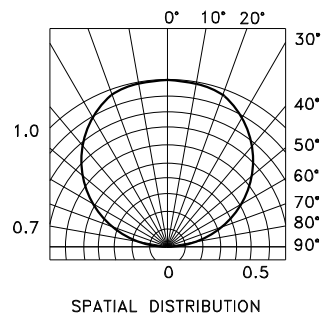
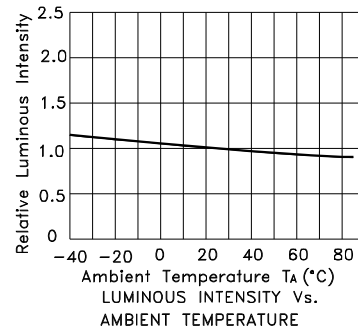
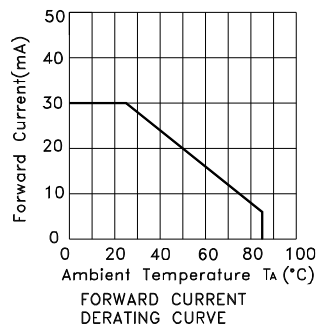
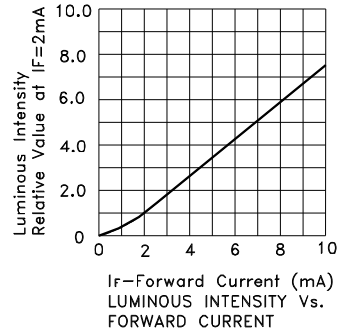
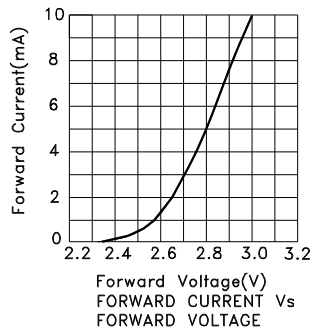
AAA3528LSEKJ3ZGKQBKS
Hyper Red



Green



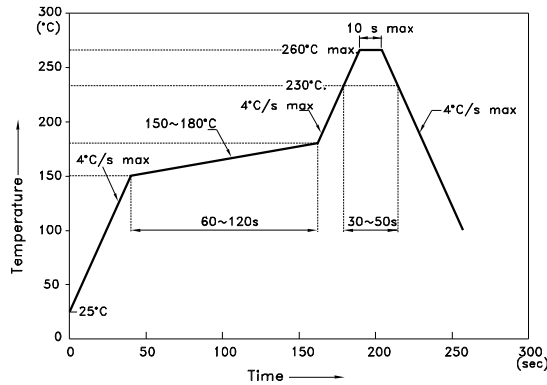
Blue



AAA3528LSEKJ3ZGKQBKS

Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

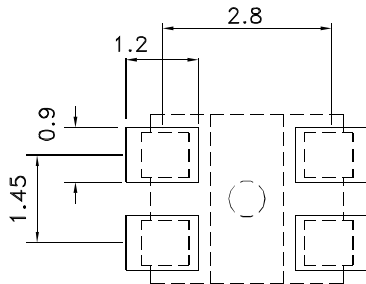
Reflow Soldering Profile For Lead-free SMT Process.



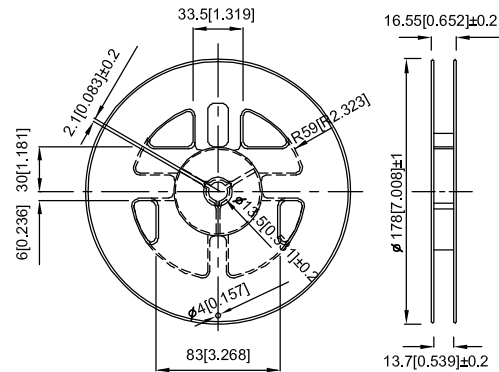
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

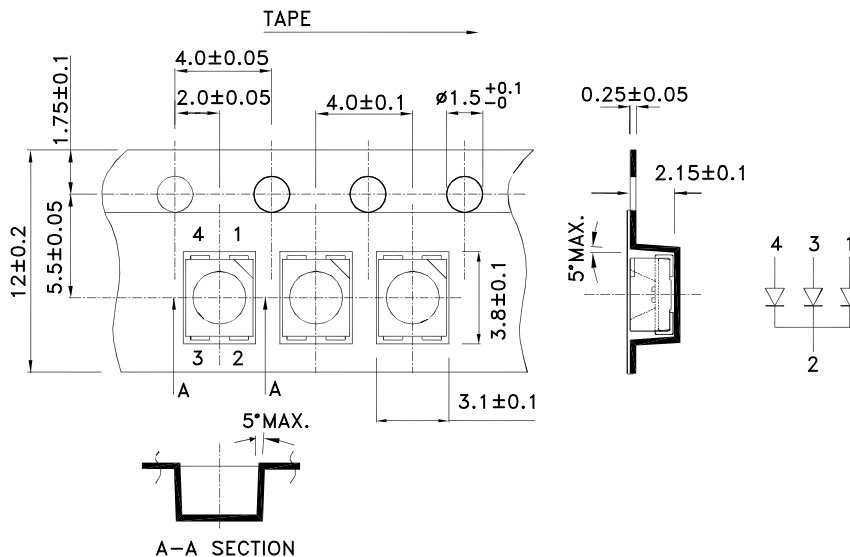
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension

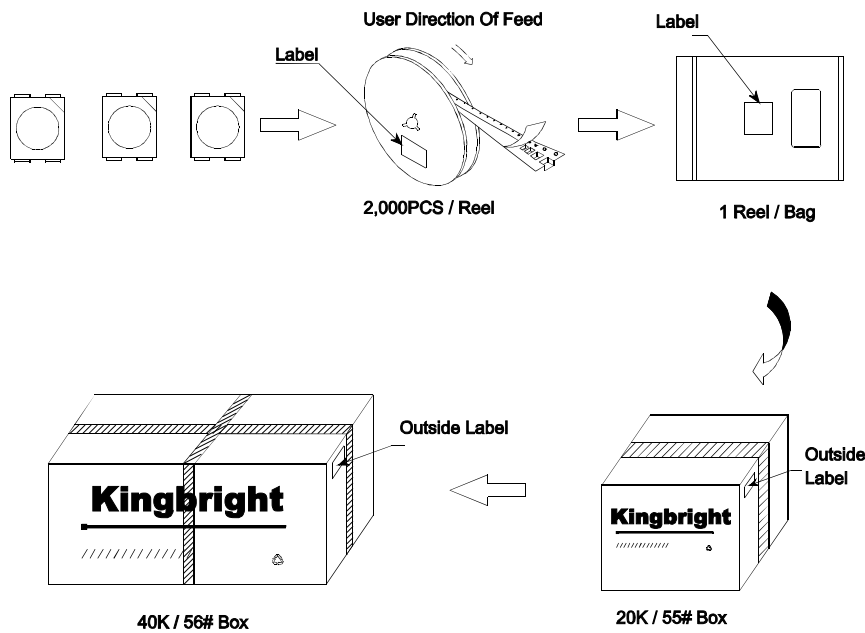



Tape Dimensions (Units : mm)



PACKING & LABEL SPECIFICATIONS

AAA3528LSEKJ3ZGKBKS



Kingbright		
P/NO: AAA3528XXX		
QTY: 2,000 PCS	Q.C.	Q.C. XXXXXXX PASSED
S/N: XXXX		
CODE: XXX		
LOT NO:		
		
RoHS Compliant		

Terms and conditions for the usage of this document

1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
4. The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance.
5. The contents and information of this document may not be reproduced or re-transmitted without permission by Kingbright.
6. All design applications should refer to Kingbright application notes available at <http://www.KingbrightUSA.com/ApplicationNotes>